

## Subfloor preparation of non suitable subfloors for direct bonding of parquet according to DIN 18356

Subfloors	Preparing	Prepare	Primer Dilution	Drying time	Bonding of reinforcement/decoupling	Reinforcement/decoupling	Primer Dilution	Drying time	Levelling
Cement screeds (CT), concrete with insufficient levelness		Grind and vacuum RS 5935 or RS 5945	D 3003 or D 3004 1:2 with water	when suitable for walking					
Calcium sulfate screeds (CA), with insufficient levelness		Grind and vacuum RS 5935 or RS 5945	D 3003 or D 3004 1:2 with water	approx. 1 hour when suitable for walking in combination with A 830					A 830 Z 610 Z 615 Z 625 Z 630 Z 635 Z 636 Z 715 Z 515
Magnesite screeds (MA), with insufficient levelness		Grind and vacuum RS 5935 or RS 5945	PU 280 PU 235 MS 330	approx. 1 hour approx. 4-6 hours approx. 1 hour			D 3045	approx. 1 hour	
Mastic asphalt screeds (AS), with insufficient levelness		Vacuum RS 5935 or RS 5945	D 3004 1:1 with water or D 3045	approx. 30-60 minutes					
Terrazzo, tiles with insufficient levelness		Cleaning with R 4515, RS 5935 or RS 5945	D 3004 undiluted or D 3045	approx. 30-60 minutes					
Old adhesive remnants on standardised subfloors		Grind and vacuum RS 5935 or RS 5945	PU 280 PU 235 MS 330	approx. 1 hour approx. 4-6 hours approx. 1 hour					
Cement screeds (CT) with to high residual humidity up to 6 CM%/98 % KRL without underfloor heating, up to 3 CM%/85 % KRL with underfloor heating, concrete with to high residual humidity up to 7.5 %/98 % KRL by weight		Grind and vacuum RS 5935 or RS 5945	PU 280 2-fold layer PU 235 2-fold layer	approx. 1 hour per layer approx. 4-6 hours per layer					A 830 Z 610 Z 615 Z 625 Z 630 Z 635 Z 636 Z 715 Z 515
Cement screeds (CT) with to high residual humidity up to 5 CM%/95 % KRL without underfloor heating, up to 3 CM%/85 % KRL with underfloor heating, concrete with to high residual humidity up to 7 %/95 % KRL by weight		Grind and vacuum RS 5935 or RS 5945	MS 330	approx. 1 hour			D 3045	approx. 1 hour	
Cement screeds (CT), concrete with insufficient surface stability		Grind and vacuum RS 5935 or RS 5945	PU 280 *1 PU 235 *1 MS 330 *1	approx. 1 hour approx. 4-6 hours per layer approx. 1 hour					
Cement screeds (CT) with to high residual humidity up to 5 CM%/95 % KRL without underfloor heating, up to 3 CM%/85 % KRL with underfloor heating		Grind and vacuum RS 5935 or RS 5945	D 3080 1:1 with water then D 3080 undiluted	at least 30 minutes  at least 120 minutes					A 830 Z 610 Z 615 Z 625 Z 630 Z 635 Z 715 Z 515
Cement screeds (CT), concrete, calcium sulfate screeds (CA), magnesite screeds (MA) or mastic asphalt screeds (AS) sufficient load-bearing but with cracks or not homogeneous (different pavings)		Grind and vacuum	PU 280 PU 235 MS 330 *3	approx. 1 hour approx. 4-6 hours approx. 1 hour	MS 230 MS 232 MS 260 MS 261 MS 262 MS 265 MS 269 MS 290	MS 292 PU 210 PU 225 PU 385 PU 215 *E PU 216 *E PU 220 *E	EM 140 *1 RP 104 *1 RP 107 *1 RP 109 *1 RP 115 *1 RP 704 *1	RP 709 *1 RP 715 *1 TS 102 *1 TS 103 *1 TS 112 *1	
Gypsum fibre boards, as far as parquet type is recommended for direct bonding by manufacturer		Vacuum			MS 228 MS 230 MS 232 MS 260 MS 261 MS 262 MS 265 MS 269	MS 290 MS 292 PU 210 PU 225 PU 385 PU 215 *E PU 216 *E PU 220 *E	EM 140 RP 104 RP 107 RP 109 RP 115 RP 704	RP 709 RP 715 TS 102 TS 103 TS 112	
Permanent existing tiles, wood planks, parquet		Cleaning of tiles with R 4515, sand entire surface			MS 228 MS 230 MS 232 MS 260 MS 261 MS 262 MS 265 MS 269	MS 290 MS 292 PU 210 PU 215 *E PU 216 *E PU 220 *E PU 225 PU 385	EM 140 RP 104 RP 107 RP 109 RP 115 RP 704	RP 709 RP 715 TS 102 TS 103 TS 112	
Permanent existing tiles, wood planks, parquet		Cleaning of tiles with R 4515, sand entire surface							Z 645 *2 Z 610 *2 Z 615 *2 Z 625 *2 Z 630 *2 Z 640 *2 D 3060 *2 +

The applicable standards and fact sheets must be heeded with all laying operations.

Please note:

\*1 Depending on subfloor stability, in case of doubt please consult Wakol technical support

\*2 If levelling is necessary

\*3 Direct installation only with MS Parquet Adhesives

\*E All mentioned products are very low in emissions, except for \*E